

ETKD-JPHOKL01-B01

Environment Test Report

Report NO:13E020007

Summary	<p><input type="checkbox"/> Pass</p> <p><input type="checkbox"/> Fail</p> <p>Note : There is/are ____ defect(s) not list in the report, please check it in the DTS Website.</p> <p><input checked="" type="checkbox"/> Pass with Deviation</p> <p>Comment: <u>Temperature points at 1 components were estimated to be in marginal temperature points in comparion with component datasheets.</u></p>
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Issue date

2013-04-16

Approval

Tom Lin

Test Engineer

Andy Chen

Test item list

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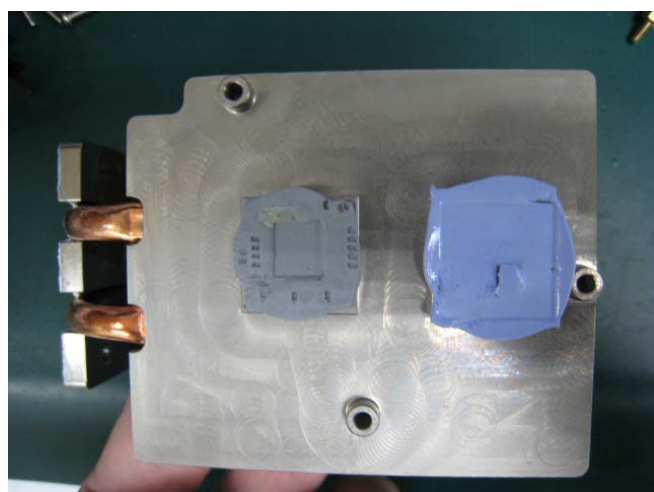
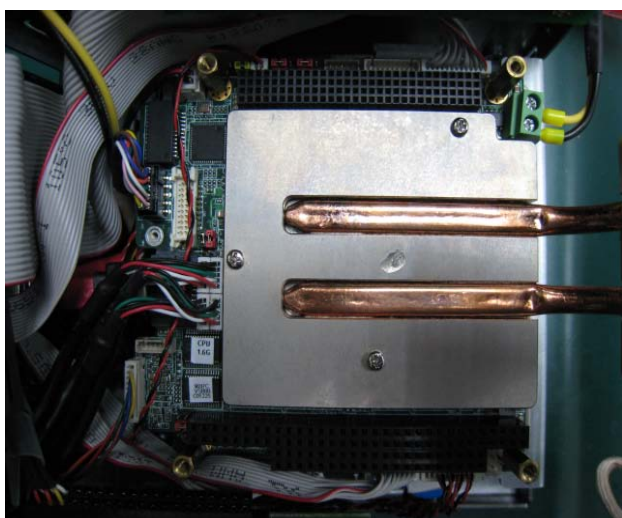
Testing Result

Num	Test item list	Result	Remark
1	Temperature rise test	Pass	
2	Temperature cycle operation test	Pass	
3	Cold start and hot start test	Pass	

Configuration of EUT

Item	Device Information	
SYSTEM PC Model / Ver.	ETKD-JPHOKI01-B01 A1.0	
CPU	Intel Atom N2600 1.6GHz	
BIOS / Version	PFM-CVS Rev.B R0.1(PFCVBM01)(02/19/2013)	
South Bridge	Intel Cedar View platform N2600	
Industrial Memory	DSL DDR3 1333 2G CL9 2UD22D9MGZ	
Industrial SSD	Innodisk FID 2.5" SATA 1000 plus – Innodisk FID 2.5" SATA 1000 plus	
Operating System	Windows 7 Professional English 64 Bit	
Adapter	FSP FSP084-DMAA1	

System picture:



Temperature rise test

Test Date: 04-15-2013

Test Product: ETKD-JPHOKI01-B01

Test Site: AAeon QE Dept.

Test Standard: Refer to EN 61131-2(94), UL508 (94)

Temperature Measurement:

40 Channel Thermal Recorder:

YOKOGAWA Inc,

Model: DA100-13-1D

Date of Calibration: 10/08/2012

Serial Number: 12A323190

Test Condition:

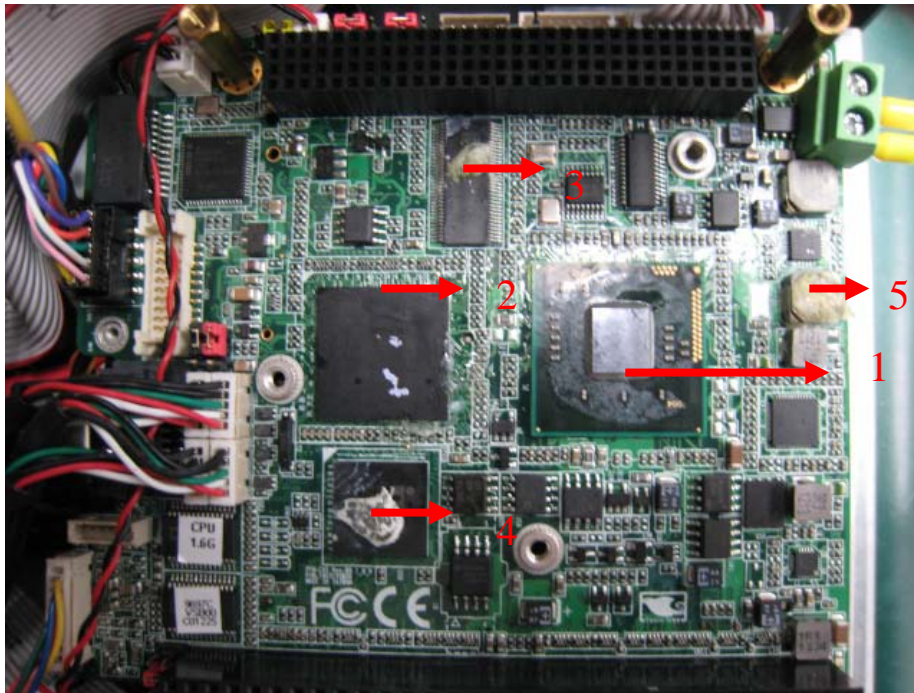
Ambient temperature: 55°C

Continuous running till thermal stable (within less than 1°C)

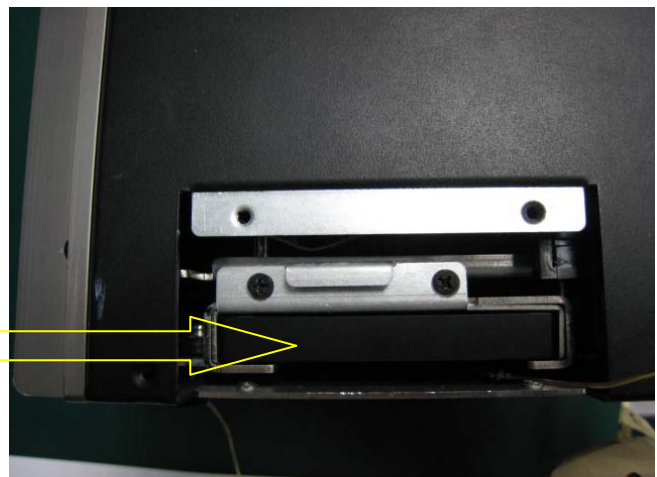
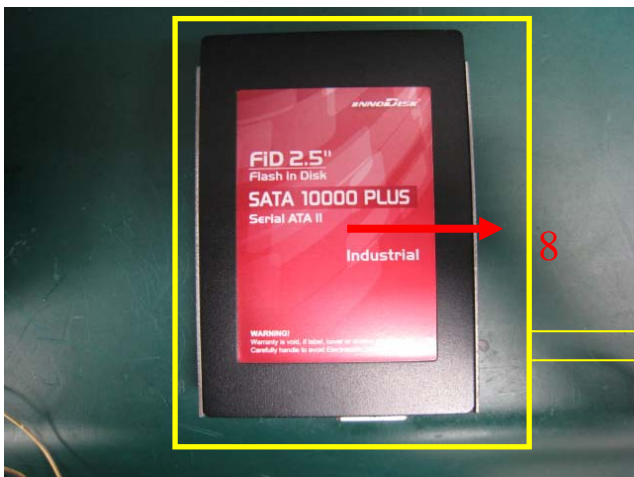
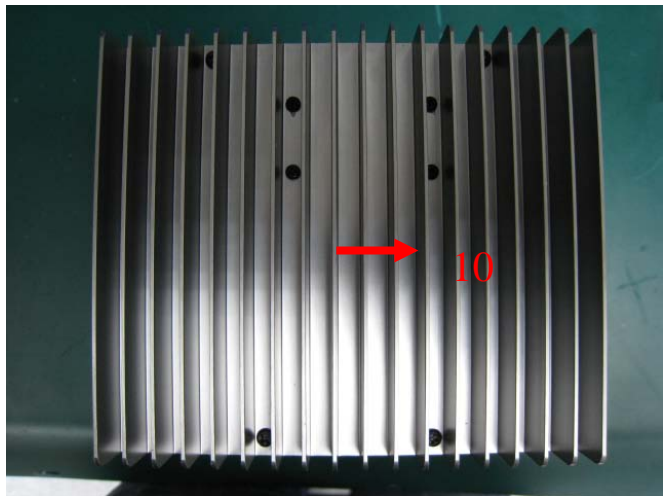
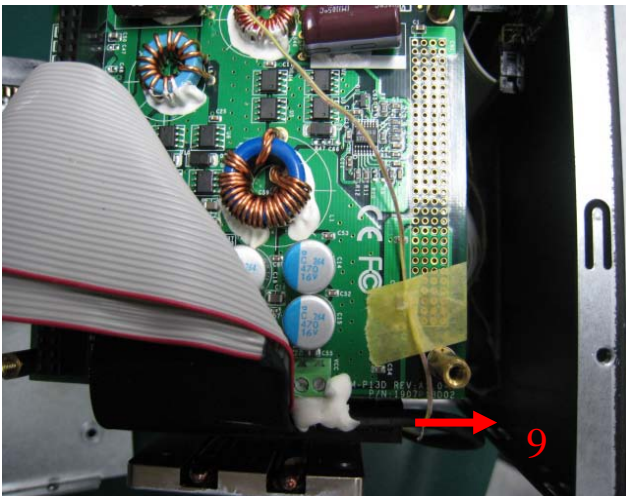
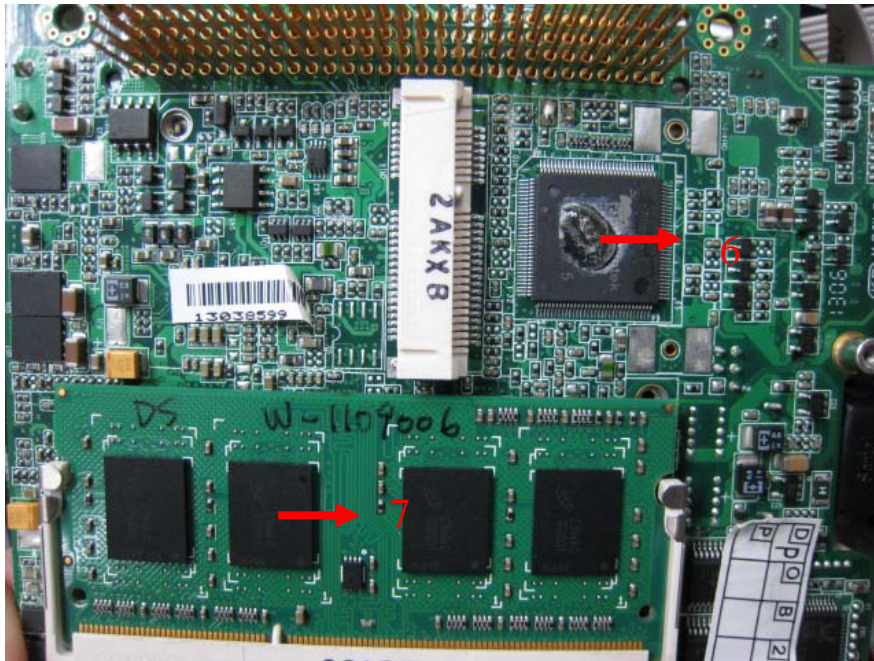
Test Software:

Windows 7 / Run PassMark Burn In Test 7.0 Pro

Terminal Recorder:



Temperature rise test



Temperature rise test

Thermal profile data:

Point	Temp. Stage(°C)	Spec	25	55	Note
01. CPU - Intel Atom N2600 1.6GHz		100	47.5	77.5	
02. U2 - (TF)IC.SMD.NM10 Express Chipset.INTEL.CG82NM10.SLGXX		115	49.5	79.6	
03. U4- IC.SMD.TSSOP64P.CLOCK GENERATOR.IDT.9LPRS501PGLF		115	54.1	84.1	
04. U58 - (TF)IC.SMD TFBGA.160P.PCI to ISA Bridge Chip.ITE.IT8888G-L		125	52.0	82.0	
05. L12 - COIL.3.3uH.20%.SMD		125	58.3	88.3	
06. U10 - (TF)IC.SMD.LQFP128P.Super I/O.Fintek.F81866D-I		125	55.1	85.1	
07. RAM - DSL DDR3 1333 2G CL9 2UD22D9MGZ		85	54.0	84.0	Note4
08. Industrial SSD – Innodisk FID 2.5" SATA 1000 plus		85	43.2	73.2	
09. Internal Air		NA	50.3	80.3	
10. External heatsink		NA	41.7	71.7	
11. Chamber Temperature		NA	25	55	

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- **Fail** : $T_m > T_c$; The measured value is over specification plus margin.
- **Margin** : $T_c > T_m > T_c - 5^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** : $T_m < T_c - 5^\circ\text{C}$; The measured value is with safety margin.

4. Defect NO. [E130203L](#)[L](#)[A](#)[B](#)[E](#)[0](#)[2](#)

Sample Configuration & Quantity Under Test:

Quantity: 1 (ETKD-JPHOKI01-B01)

Test Result:

No issues were found during the temperature rise operation test.

Temperature cycle test

Test Date: 04-11 ~15-2013

Test Product: ETKD-JPHOKI01-B01

Test Site: AAEON QE Dept.

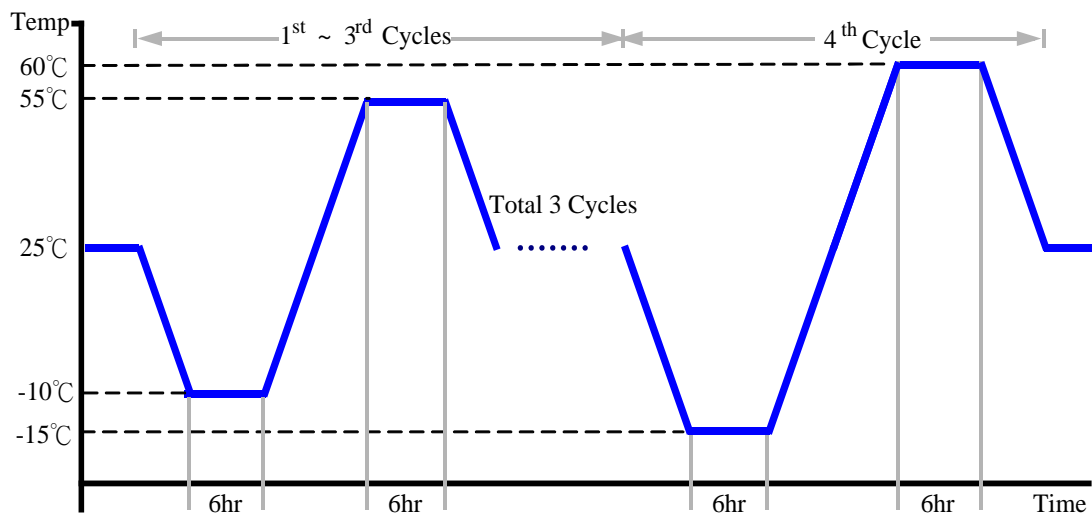
Test Standard: Refer to IEC68-2-14 Testing procedures
Test N: Change of temperature Test

Test Equipment:

Programmable Temperature & Humidity Chamber(K.SON. INS. TECH. CORP.)
Model: THS-D75-100+LN2
Date of Calibration: 06/20/2012
Serial Number: 6487KT

Test Condition:

1. Test Low Temperature: -10°C (1~3 cycles)
-15°C (4th cycle)
2. Test High Temperature: 55°C (1~3 cycles)
60°C (4th cycle)
3. Test dwell time: 6Hrs
4. Temperature slope: 2°C/min
5. Test cycle: 4 cycles
6. Test Environment Curve:



Sample Configuration & Quantity Under Test:

Quantity: 1 (ETKD-JPHOKI01-B01)

Test Result:

No issues were found during the temperature operation cycle test.

